

Vishay Semiconductors

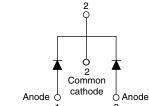
# Ultrafast Rectifier, 2 x 8 A FRED Pt®





T<sub>J</sub> max.

Diode variation



Base common

cathode

175 °C

Common cathode

| PRODUCT SUMMARY                  |                    |  |  |  |  |  |
|----------------------------------|--------------------|--|--|--|--|--|
| Package                          | TO-220AB           |  |  |  |  |  |
| I <sub>F(AV)</sub>               | 2 x 8 A            |  |  |  |  |  |
| $V_{R}$                          | 200 V              |  |  |  |  |  |
| V <sub>F</sub> at I <sub>F</sub> | 0.975 V            |  |  |  |  |  |
| t <sub>rr</sub> typ.             | See Recovery table |  |  |  |  |  |

#### **FEATURES**

- Ultrafast recovery time
- · Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- Compliant to RoHS Directive 2002/95/EC
- Designed and qualified according to JEDEC-JESD47
- Halogen-free according to IEC 61249-2-21 definition (-N3 only)





RoHS

HALOGEN FREE Available

#### **DESCRIPTION/APPLICATIONS**

VS-MUR1620CTPbF is the state of the art ultrafast recovery rectifier specifically designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

| ABSOLUTE MAXIMUM RATINGS                  |              |                                   |   |             |       |  |  |
|---|--------------|-----------------------------------|---|-------------|-------|--|--|
| PARAMETER                                 |              | SYMBOL                            | TEST CONDITIONS   | MAX.        | UNITS |  |  |
| Peak repetitive reverse voltage           |              | $V_{RRM}$                         |   | 200         | V     |  |  |
| per l                                     |              |                                   |   | 8.0         |       |  |  |
| Average rectified forward current to      | total device | I <sub>F(AV)</sub>                | Rated V <sub>R</sub> , T <sub>C</sub> = 150 °C                      | 16          | ^     |  |  |
| Non-repetitive peak surge current per leg |              | I <sub>FSM</sub>                  |   | 100         | Α     |  |  |
| Peak repetitive forward current per       | leg          | I <sub>FM</sub>                   | Rated V <sub>R</sub> , square wave, 20 kHz, T <sub>C</sub> = 150 °C | 16          |       |  |  |
| Operating junction and storage tem        | peratures    | T <sub>J</sub> , T <sub>Stg</sub> |   | - 65 to 175 | °C    |  |  |

| <b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified) |                                     |  |      |      |       |       |  |
|--|-------------------------------------|--|------|------|-------|-------|--|
| PARAMETER  | SYMBOL                              | TEST CONDITIONS  | MIN. | TYP. | MAX.  | UNITS |  |
| Breakdown voltage,<br>blocking voltage   | V <sub>BR</sub> ,<br>V <sub>R</sub> | Ι <sub>R</sub> = 100 μΑ  | 200  | -    | -     |       |  |
| Forward voltage  | V <sub>F</sub>                      | I <sub>F</sub> = 8 A   | -    | -    | 0.975 | V     |  |
|  |                                     | I <sub>F</sub> = 8 A, T <sub>J</sub> = 150 °C                  | -    | -    | 0.895 |       |  |
| Reverse leakage current I <sub>R</sub>   |                                     | $V_R = V_R$ rated  | -    | -    | 5     |       |  |
|  |                                     | T <sub>J</sub> = 150 °C, V <sub>R</sub> = V <sub>R</sub> rated | -    | -    | 250   | μΑ    |  |
| Junction capacitance   | C <sub>T</sub>                      | V <sub>R</sub> = 200 V   | -    | 25   | -     | pF    |  |
| Series inductance  | L <sub>S</sub>                      | Measured lead to lead 5 mm from package body                   | -    | 8.0  | -     | nΗ    |  |



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| <b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified) |                  |   |  |      |      |       |     |  |
|---|------------------|---|--|------|------|-------|-----|--|
| PARAMETER   | SYMBOL           | TEST CO   | MIN.   | TYP. | MAX. | UNITS |     |  |
| Reverse recovery time   |                  | $I_F = 1.0 \text{ A, } dI_F/dt =$   | 50 A/μs, V <sub>R</sub> = 30 V   | -    | -    | 35    |     |  |
|   |                  | I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>REC</sub> = 0.25 A |  | -    | -    | 25    |     |  |
|   | t <sub>rr</sub>  | T <sub>J</sub> = 25 °C  | I <sub>F</sub> = 8 A<br>dI <sub>F</sub> /dt = 200 A/μs<br>V <sub>R</sub> = 160 V | -    | 20   | -     | ns  |  |
|   |                  | T <sub>J</sub> = 125 °C   |  | -    | 34   | -     |     |  |
| Peak recovery current   | I <sub>RRM</sub> | T <sub>J</sub> = 25 °C  |  | -    | 1.7  | -     | А   |  |
|   |                  | T <sub>J</sub> = 125 °C   |  | -    | 4.2  | -     | A   |  |
| Reverse recovery charge   | 0                | T <sub>J</sub> = 25 °C  |  | -    | 23   | -     | 200 |  |
|   | $Q_{rr}$         | T <sub>J</sub> = 125 °C   |  | -    | 75   | -     | nC  |  |

| THERMAL - MECHANICAL SPECIFICATIONS             |                                   |  |              |      |            |                        |  |
|---|-----------------------------------|--|--------------|------|------------|------------------------|--|
| PARAMETER                                       | SYMBOL                            | TEST CONDITIONS                            | MIN.         | TYP. | MAX.       | UNITS                  |  |
| Maximum junction and storage temperature range  | T <sub>J</sub> , T <sub>Stg</sub> |  | - 65         | -    | 175        | °C                     |  |
| Thermal resistance, junction to case per leg    | R <sub>thJC</sub>                 |  | -            | -    | 3.0        |                        |  |
| Thermal resistance, junction to ambient per leg | R <sub>thJA</sub>                 |  | -            | -    | 50         | °C/W                   |  |
| Thermal resistance, case to heatsink            | R <sub>thCS</sub>                 | Mounting surface, flat, smooth and greased | -            | 0.5  | -          |                        |  |
| Woight  |                                   |  | -            | 2.0  | -          | g                      |  |
| Weight  |                                   |  | -            | 0.07 | -          | OZ.                    |  |
| Mounting torque                                 |                                   |  | 6.0<br>(5.0) | -    | 12<br>(10) | kgf · cm<br>(lbf · in) |  |
| Marking device                                  |                                   | Case style TO-220AB                        |              | MUR1 | 620CT      | •                      |  |

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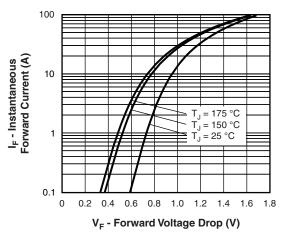


Fig. 1 - Typical Forward Voltage Drop Characteristics

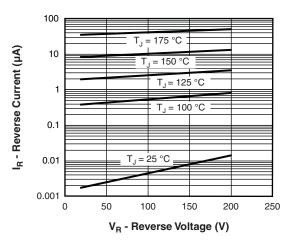


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

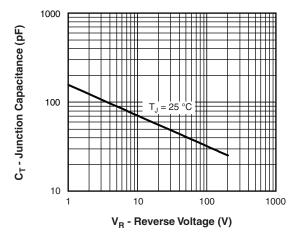


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

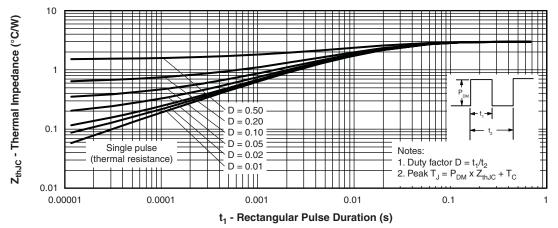
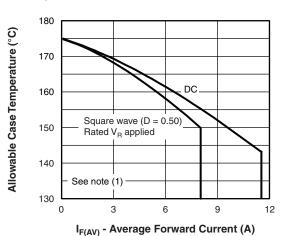


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics



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Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

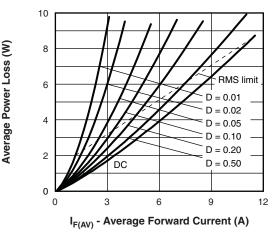


Fig. 6 - Forward Power Loss Characteristics

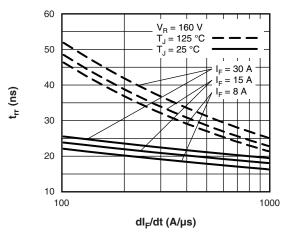


Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

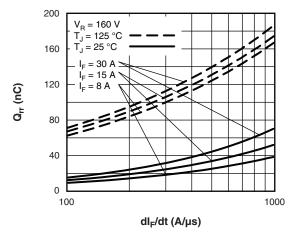


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt

#### Note

 $^{(1)}$  Formula used:  $T_{C} = T_{J}$  - (Pd + Pd\_{REV}) x  $R_{thJC};$  $Pd = Forward\ power\ loss = I_{F(AV)}\ x\ V_{FM}\ at\ (I_{F(AV)}/D)\ (see\ fig.\ 6);$   $Pd_{REV} = Inverse\ power\ loss = V_{R1}\ x\ I_R\ (1\ -\ D);\ I_R\ at\ V_{R1} = Rated\ V_R$ 

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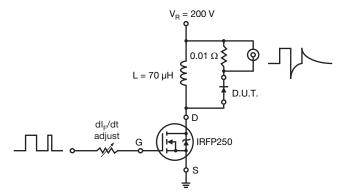
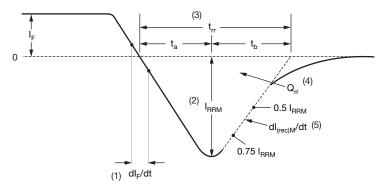


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl<sub>F</sub>/dt rate of change of current through zero crossing
- (2) I<sub>RRM</sub> peak reverse recovery current
- (3)  $\rm t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $\rm I_F$  to point where a line passing through 0.75  $\rm I_{RRM}$  and 0.50  $\rm I_{RRM}$  extrapolated to zero current.
- (4)  $\mathbf{Q}_{\rm rr}$  area under curve defined by  $\mathbf{t}_{\rm rr}$  and  $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

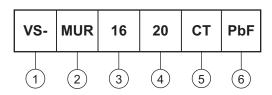
(5)  $dI_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$ 

Fig. 10 - Reverse Recovery Waveform and Definitions

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### **ORDERING INFORMATION TABLE**

**Device code** 



1 - Vishay Semiconductors product

2 - Ultrafast MUR series

3 - Current rating (16 = 16 A)

4 - Voltage rating (20 = 200 V)

5 - CT = Center tap (dual)

6 - Environmental digit:

PbF = Lead (Pb)-free and RoHS compliant

-N3 = Halogen-free, RoHS compliant and totally lead (Pb)-free

| ORDERING INFORMATION (Example) |                  |                        |                         |  |  |  |  |
|--------------------------------|------------------|------------------------|-------------------------|--|--|--|--|
| PREFERRED P/N                  | QUANTITY PER T/R | MINIMUM ORDER QUANTITY | PACKAGING DESCRIPTION   |  |  |  |  |
| VS-MUR1620CTPbF                | 50               | 1000                   | Antistatic plastic tube |  |  |  |  |
| VS-MUR1620CT-N3                | 50               | 1000                   | Antistatic plastic tube |  |  |  |  |

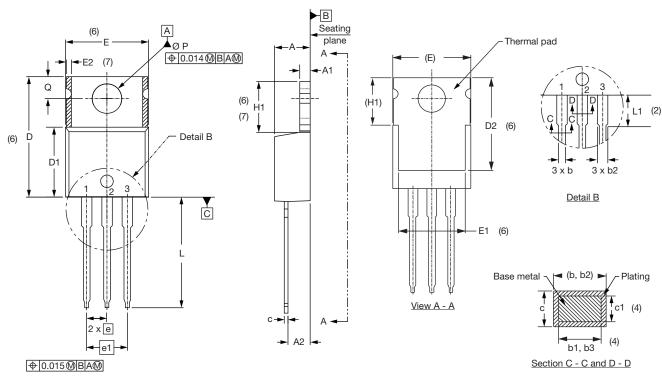
| LINKS TO RELATED DOCUMENTS |             |                          |  |  |  |
|----------------------------|-------------|--------------------------|--|--|--|
| Dimensions                 |             | www.vishay.com/doc?95222 |  |  |  |
| Part marking information   | TO-220ABPbF | www.vishay.com/doc?95225 |  |  |  |
| Fait marking imormation    | TO-220AB-N3 | www.vishay.com/doc?95028 |  |  |  |



### Vishay Semiconductors

### **TO-220AB**

#### **DIMENSIONS** in millimeters and inches



### Lead assignments

#### **Diodes**

- 1. Anode/open
- 2. Cathode
- 3. Anode

#### Conforms to JEDEC outline TO-220AB

| MILLIMETERS |  | INCHES  |  | NOTES   |
|-------------|--|---|--|---|
| MIN.        | MAX.   | MIN.  | MAX.   | NOTES   |
| 4.25        | 4.65   | 0.167   | 0.183  |   |
| 1.14        | 1.40   | 0.045   | 0.055  |   |
| 2.56        | 2.92   | 0.101   | 0.115  |   |
| 0.69        | 1.01   | 0.027   | 0.040  |   |
| 0.38        | 0.97   | 0.015   | 0.038  | 4   |
| 1.20        | 1.73   | 0.047   | 0.068  |   |
| 1.14        | 1.73   | 0.045   | 0.068  | 4   |
| 0.36        | 0.61   | 0.014   | 0.024  |   |
| 0.36        | 0.56   | 0.014   | 0.022  | 4   |
| 14.85       | 15.25  | 0.585   | 0.600  | 3   |
| 8.38        | 9.02   | 0.330   | 0.355  |   |
| 11.68       | 12.88  | 0.460   | 0.507  | 6   |
|             | MIN. 4.25 1.14 2.56 0.69 0.38 1.20 1.14 0.36 0.36 14.85 8.38 | MIN.         MAX.           4.25         4.65           1.14         1.40           2.56         2.92           0.69         1.01           0.38         0.97           1.20         1.73           1.14         1.73           0.36         0.61           0.36         0.56           14.85         15.25           8.38         9.02 | MIN.         MAX.         MIN.           4.25         4.65         0.167           1.14         1.40         0.045           2.56         2.92         0.101           0.69         1.01         0.027           0.38         0.97         0.015           1.20         1.73         0.047           1.14         1.73         0.045           0.36         0.61         0.014           0.36         0.56         0.014           14.85         15.25         0.585           8.38         9.02         0.330 | MIN.         MAX.         MIN.         MAX.           4.25         4.65         0.167         0.183           1.14         1.40         0.045         0.055           2.56         2.92         0.101         0.115           0.69         1.01         0.027         0.040           0.38         0.97         0.015         0.038           1.20         1.73         0.047         0.068           1.14         1.73         0.045         0.068           0.36         0.61         0.014         0.024           0.36         0.56         0.014         0.022           14.85         15.25         0.585         0.600           8.38         9.02         0.330         0.355 |

| SYMPOL   | SYMBOL MILLIMETERS INCHES |       | HES   | NOTES |       |
|----------|---------------------------|-------|-------|-------|-------|
| STIVIBOL | MIN.                      | MAX.  | MIN.  | MAX.  | NOTES |
| Е        | 10.11                     | 10.51 | 0.398 | 0.414 | 3, 6  |
| E1       | 6.86                      | 8.89  | 0.270 | 0.350 | 6     |
| E2       | -                         | 0.76  | -     | 0.030 | 7     |
| е        | 2.41                      | 2.67  | 0.095 | 0.105 |       |
| e1       | 4.88                      | 5.28  | 0.192 | 0.208 |       |
| H1       | 6.09                      | 6.48  | 0.240 | 0.255 | 6, 7  |
| L        | 13.52                     | 14.02 | 0.532 | 0.552 |       |
| L1       | 3.32                      | 3.82  | 0.131 | 0.150 | 2     |
| ØΡ       | 3.54                      | 3.73  | 0.139 | 0.147 |       |
| Q        | 2.60                      | 3.00  | 0.102 | 0.118 |       |
| θ        | 90° to 93°                |       | 90° t | o 93° |       |
|          | •                         |       |       |       |       |

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimensions E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC TO-220, except A2 (maximum) and D2 (minimum) where dimensions are derived from the actual package outline

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Lead tip



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Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

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